

SPUTTERING TARGET AND MAGNETIC FILM

ABSTRACT

Provided is a sputtering target, comprising: from 0.001 mol% to 0.5 mol% of Bi; from 45 mol% or less of Cr; 45 mol% or less of Pt; 60 mol% or less of Ru; and a total of 1 mol% to 35 mol% of at least one metal oxide, the balance being Co and inevitable impurities.